



Final Product Change Notification

201301005F01

Issue Date: 18-Nov-2013
Effective Date: 16-Feb-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to [view this notification online](#)



Management Summary

TDA8579 diffusion process will be transferred from ASMC 5 to ASMC 6 inch

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input checked="" type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling

Wafer Fab Transfer of TDA8579 from ASMC 5 inch to 6 inch

Details of this Change

The following changes are applied:

1. Change from 5 inch wafer diameter to 6 inch diameter processing (same fab ASMC)
2. Change of molding compound from GE7470L-AL to GE7470L-Q
3. Change of marking on the IC
4. Datasheet, Philips logo changed to NXP logo

Why do we Implement this Change

NXP follows the industrial trend to move to more modern fabs and green material.

The TDA8579 is a mature low power Audio Amplifier consumer product, which is currently manufactured in the BIP420 (COBI-1) process on 5 inch line at the wafer fab ASMC (Shanghai, China).

The 5 inch production line at ASMC reaches end of life and corresponding 5 inch products need to be discontinued or transferred to the ASMC 6 inch line.

Since the market demand for the TDA8579 remains stronger than expected we plan to transfer the TDA8579 to the same BIP420 (COBI-1) process on the 6 inch production line at ASMC.
The process and material are run within automotive production environment but the design of the product was not automotive qualified nor is there any intention to do so now.
This move is also in line with our industrial strategy to move production to more modern fabs. ASMC is a proven wafer fab for automotive production.
In line with this move the SO8 package will also be changed and improved to the dark green material, which is also qualified and running in automotive conditions.

Identification of Affected Products

Replacement part type created, see Parts Affected list
Affected product is shown in this ePCN

Product Availability

Sample Information

Samples are available from 08-Nov-2013

Production

Planned first shipment 11-Nov-2013

Impact

no impact to the product's functionality anticipated.
No change datasheet values except Philips logo changed to NXP logo

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201301005A	21-Jan-2013		Wafer Fab Transfer of TDA8579 from ASMC 5 inch to 6 inch
201301005AU01	26-Jan-2013		Wafer Fab Transfer of TDA8579 from ASMC 5 inch to 6 inch

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 18-Dec-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Peter Krys
Position Partnership Manager
e-mail address peter.krys@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.